

Ab --13. (new) A part according to claim 11, wherein the slit is formed on the side plate so as to have a predetermined length in a direction of the leg.

REMARKS

The specification has been amended as needed so as to place the application in condition for disposal at the time of the next Official Action.

The claims previously in the case have been replaced by a set of new claims that are believed to be proper as to form and clearly patentable over the cited references.

Reconsideration is accordingly respectfully requested, for the rejection of the claims as anticipated by HENSCHEN 5,288,959 or YAMADA et al. 4,939,498 or NOSCHESSE 4,767,344 or YASUI 4,617,585, or as unpatentable over YAMADA et al. or YASUI.

There are several novel aspects of the present invention that are brought out in the new claims. In new claim 8, the relative length of the legs and the plates on the other side of the slits is emphasized. Thus, the plate on the side of the slits opposite the legs is shorter, so that the leg can protrude through a hole in the printed circuit board and the plate on the side of the slit opposite the leg serves as a stop, thereby correctly to position the leg for the soldering operation. We do not find this in the prior art.

Claim 9 is specific to the Figure 3 arrangement and claim 10 is specific to the Figure 1 arrangement.

New claims 11-13 are also inserted, specific to the Figure 1 arrangement, which has no counterpart in the cited references.

In view of the present amendment and the foregoing remarks, therefore, it is believed that this application has been placed in condition for allowance, and reconsideration and allowance are respectfully requested.

Attached hereto is a marked-up version showing the changes made to the specification. The attached page is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE."

Respectfully submitted,

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KADOKAWA S.N. 09/995,591

**"VERSION WITH MARKINGS TO SHOW CHANGES MADE"**

IN THE SPECIFICATION:

Page 1, the paragraph, beginning on line 34, bridging pages 1 and 2, has been amended as follows:

--For example, Japanese Laid-Open Utility Model application No. 5-95092 discloses the attachment manner of a heat radiating plate that offers improved soldering reliability when the soldering iron is used. This [head] heat radiating plate is shown in FIG. 4. As shown, the heat radiating plate 2 has engaging portions 2a which are inserted into the attachment holes 1a of the printed wiring board 1, and small holes 2b are formed on the heat radiating plate 2 near the engaging portions 2a. With the heat radiating plate 2 thus configured, when the engaging portions 2a are heated by the soldering iron, the small holes 2b prevent the heat applied to the engaging portions 2a from radiating via the heat radiating plate, and thus the soldering operation can be easily performed.--.

Page 5, the paragraph, beginning on line 1, has been amended as follows:

--Then, the surface of the printed wiring board 20 which is formed with the copper foil lands 23 and the copper foil pattern 26 is dipped in the melting [noload] nolead solder in the solder tank of the soldering device (not shown) for a predetermined time period. By this, the terminals 14 of the three-terminal regulator 13 are soldered to the copper foil

pattern 26, and the legs 11 of the heat radiating plate 50 are soldered to the copper foil lands 23.--;

the paragraph, beginning on line 8, has been amended as follows:

--When the legs 11 of the heat radiating plate 50 are heated by being dipped into the [noload] nolead solder tank, the heat radiating plate 50 radiates the heat from the body unit 10 (i.e., the main plate 10a and the side plates 10b). However, according to the heat radiating plate 50 of the present invention, since the slits 12 are formed adjacent to the legs 11, the heat radiation effect by the legs 11 are quite small, and the temperature decrease of the [noload] nolead solder around the legs 11 can be suppressed to a minimum degree. Therefore, as shown in FIG. 2, the heat radiating plate 50 is securely soldered to the copper foil lands 23.--.

Page 6, the paragraph, beginning on line 12, has been amended as follows:

--When the printed wiring board 24 to which the bus bar 60 thus configured is attached is dipped into the [noload] nolead solder tank, the slits 18 [suppresses] suppress the temperature decrease of the [noload] nolead solder around the legs 17. Therefore, the legs 11 are securely soldered to the copper foil lands of the printed wiring board 24.--;

the paragraph, beginning on line 28, has been amended as follows:

KADOKAWA S.N. 09/995,591

--As described above, the present invention provides parts suitable for mass production and securely soldered to a print wiring board by a solder dipping device that uses [noload] nolead solder having high melting point.--.